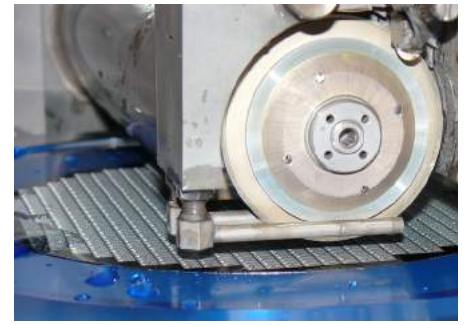


Subcontract Wafer Services

Full Turnkey Wafer Processing Services



Wafer Bumping

- Solder, gold & copper pillar bumping

Wafer Mapping / Wafer Inking

- Conversion between industry formats
- Inking using any electronic wafer map

Wafer Thinning

- Automated in-feed grinding of wafers
- Ability to saw, sort and inspect wafers down to 20 μ

Wafer Dicing

- Wafer sizes up to 12" / 300 mm
- Multi-project wafer dicing
- $\pm 1 \mu$ tolerance

Die Plating / Pick & Place

- Automated, virtually contactless handling of singulated die
- Compatible with all electronic wafer maps
- Multiple bin / grade die picking
- Safe handling of sensitive topside & 3D features

Visual Inspection

- Acceptable Quality Level (AQL)
- MIL-STD (commercial, military and aerospace grades)
- Inspection via AOI equipment available

Customized Output

- Sawn wafer on film-frame and ring-frame
- Waffle pack; Gel-Pak®, Tape & Reel
- Reconstructed wafer

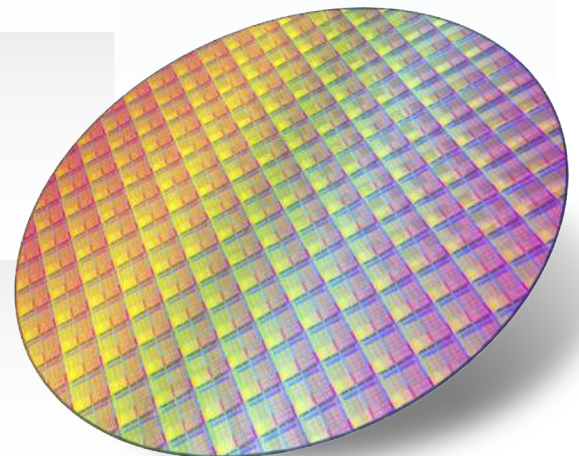
**40+ years processing
experience**

High volume capacity

**Low volume flexibility
for developments
and R&D**

Quality Certifications

- AS9100
- ISO 9001: 2015
- DLA Lab Suitability (MIL-STD-883)
- MIL-PRF-38535 Q and V (Assembly & Test)
 - Crewe UK (QML Q, V, Y for Column Attach)
- MIL-PRF-38534 Class H
- ITAR Registered
- Trusted Source (DMEA)

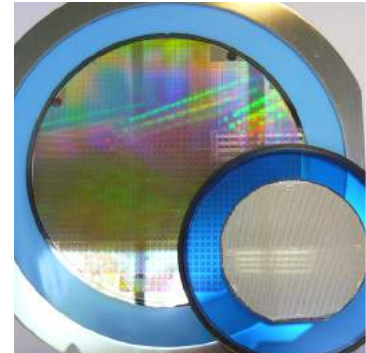


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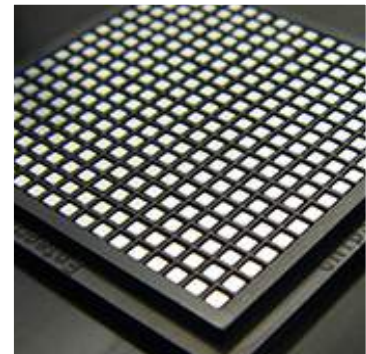
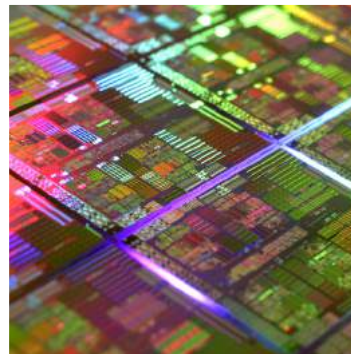


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About Micross

Micross is the global one-source provider of Bare Die & Wafers, Advanced Interconnect Technology, Custom Packaging & Assembly, Component Modification Services, Electrical & Environmental Testing and Hi-Rel Products to manufacturers and users of semiconductor devices. In business for more than 40 years, our extensive hi-reliability capabilities serve the Aerospace & Defense, Space, Medical and Industrial markets. Micross possesses the sourcing, packaging, assembly, engineering, test and logistics expertise needed to support an application throughout its entire program cycle.